

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) An IC card comprising:
a substrate having a contact hole;
a display device equipped on one side of the substrate; and
a thin film integrated circuit equipped on the other side of the substrate,
wherein the display device is electrically connected to the thin film integrated circuit through the contact hole, and
wherein each of the display device and the thin film integrated circuit comprises a polycrystalline semiconductor film.
2. (Original) An IC card according to claim 1, wherein the display device is a liquid crystal display device or a light emitting device.
3. (Canceled)
4. (Previously Presented) An IC card comprising:
a substrate having a contact hole;
a display device equipped on one side of the substrate; and
a thin film integrated circuit equipped on the other side of the substrate,
wherein the display device is electrically connected to the thin film integrated circuit through the contact hole,
wherein each of the display device and the thin film integrated circuit comprises a polycrystalline semiconductor film, and
wherein the IC card has a thickness of from 0.05 mm to 1 mm.

5. (Original) An IC card according to claim 4, wherein the display device is a liquid crystal display device or a light emitting device.

6. (Canceled)

7. (Previously Presented) An IC card comprising:
a substrate having a contact hole;
a display device equipped on one side of the substrate; and
a thin film integrated circuit equipped on the other side of the substrate,
wherein the display device is electrically connected to the thin film integrated circuit through the contact hole,
wherein each of the display device and the thin film integrated circuit comprises a polycrystalline semiconductor film, and
wherein the display device is a passive matrix type or an active matrix type, and
wherein the IC card has a thickness of from 0.05 mm to 1 mm.

8. (Original) An IC card according to claim 7, wherein the display device is a liquid crystal display device or a light emitting device.

9. (Canceled)

10. (Previously Presented) An IC card comprising:
a substrate having a contact hole;
a display device equipped on one side of the substrate; and
a plurality of thin film integrated circuits equipped on the other side of the substrate,

wherein the display device is electrically connected to the plurality of thin film integrated circuits through the contact hole,

wherein each of the display device and the plurality of thin film integrated circuits comprises a polycrystalline semiconductor film,

wherein the plurality of thin film integrated circuits are laminated, and

wherein the IC card has a thickness of from 0.05 mm to 1 mm.

11. (Original) An IC card according to claim 10, wherein thicknesses of the plurality of thin film integrated circuits are each from 1 μm to 5 μm .

12. (Original) An IC card according to claim 10, wherein the display device is a liquid crystal display device or a light emitting device.

13. (Canceled)

14. (Previously Presented) An IC card according to claim 1, wherein the substrate is a printed wiring board.

15. (Previously Presented) An IC card according to claim 14, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

16. (Previously Presented) An IC card according to claim 1, wherein the display device is equipped on one side of the substrate by an adhesive agent.

17. (Previously Presented) An IC card according to claim 1, further comprising a plurality of antenna coils.

18. (Previously Presented) An IC card according to claim 4, wherein the substrate is a printed wiring board.

19. (Previously Presented) An IC card according to claim 18, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

20. (Previously Presented) An IC card according to claim 4, wherein the display device is equipped on one side of the substrate by an adhesive agent.

21. (Previously Presented) An IC card according to claim 4, further comprising a plurality of antenna coils.

22. (Previously Presented) An IC card according to claim 7, wherein the substrate is a printed wiring board.

23. (Previously Presented) An IC card according to claim 22, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

24. (Previously Presented) An IC card according to claim 7, wherein the display device is equipped on one side of the substrate by an adhesive agent.

25. (Previously Presented) An IC card according to claim 7, further comprising a plurality of antenna coils.

26. (Previously Presented) An IC card according to claim 10, wherein the substrate is a printed wiring board.

27. (Previously Presented) An IC card according to claim 26, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

28. (Previously Presented) An IC card according to claim 10, wherein the display device is equipped on one side of the substrate by an adhesive agent.

29. (Previously Presented) An IC card according to claim 10, further comprising a plurality of antenna coils.

30. (New) An IC card according to claim 1, further comprising:
a lead provided on the substrate;
a terminal provided in the display device;
a first wire electrically connected to the lead and the terminal; and
a second wire electrically connected to the lead and at least one of the plurality of thin film integrated circuits.

31. (New) An IC card according to claim 4, further comprising:
a lead provided on the substrate;
a terminal provided in the display device;
a first wire electrically connected to the lead and the terminal; and
a second wire electrically connected to the lead and at least one of the plurality of thin film integrated circuits.

32. (New) An IC card according to claim 7, further comprising:
a lead provided on the substrate;
a terminal provided in the display device;

a first wire electrically connected to the lead and the terminal; and
a second wire electrically connected to the lead and at least one of the plurality of
thin film integrated circuits.

33. (New) An IC card according to claim 10, further comprising:
a lead provided on the substrate;
a terminal provided in the display device;
a first wire electrically connected to the lead and the terminal; and
a second wire electrically connected to the lead and at least one of the plurality of
thin film integrated circuits.